Amendments to the Specification:

Please replace paragraph [0066] with the following amended paragraph:

[0066] Table 1

		~~Relevant to claims for Epoxy (a)~~ ~~Relevant to claims for Epoxy (b)~~			
		Example 1	Example 2	Example 3	Example 4
Epoxy resin	Epoxy (a)	Epoxy 1 (112.5 pbw)	Epoxy 2 (118.8 pbw)	Epoxy 3 (118.8 pbw)	Epoxy 4 (118.8 pbw)
	Epoxy (b)	Epoxy 7 (10 pbw)	Epoxy 8 (5 pbw)	Epoxy 9 (5 pbw)	Epoxy 8 (5 pbw)
		—	Epoxy 10 (3 pbw)	Epoxy 10 (5 pbw)	—
Curing agent		Curing agent 1 (39.5 pbw)	Curing agent 1 (44.0 pbw)	Curing agent 2 (34.2 pbw)	Curing agent 3 (29.2 pbw)
Curing accelerator		Accelerator 1 (0.13 pbw)	Accelerator 1 (0.13 pbw)	Accelerator 1 (0.13 pbw)	Accelerator 1 (0.13 pbw)
Organic solvent		Organic solvent 2 (18.6 pbw)	Organic solvent 2 (35 pbw)	Organic solvent 1 (8 pbw)	Organic solvent 2 (22.9 pbw)
				Organic solvent 2 (17.6 pbw)	Organic solvent 3 (22.9 pbw)
				Organic solvent 3 (25.6 pbw)	
Inorganic filler		—	—	—	—
Ratio of epoxy (a)+ epoxy (b) as a solid content per whole epoxy resin		100%	97%	95%	100%
Proportion of epoxy (a) as solid content per whole epoxy resin		90%	92%	90%	95%
Bromine content (%) in epoxy resin		23%	18.4%	18.1%	19%
Appearance of prepreg		Good	Good	Good	Good
Glass transition temperature		o(135□)	o(135□)	o(130□)	o(132□)
Fire retardancy		V-0	V-0	V-0	V-0
Moldability		o	o	□	o
Curing time for prepreg (second)	60 seconds	o	o	×	o
	80 seconds	o	o	o	o
	100 seconds	o	o	o	o
	140 seconds	o	o	o	o
	180 seconds	o	o	o	o
Coefficient of thermal expansion (αz1)		65 ppm	65 ppm	65 ppm	65 ppm
Heat resistance in oven		270□	270□	265□	270□
Thermal decomposition temperature (weight loss by 5%)		355□	355□	350□	355□

		~~Relevant to claims for epoxy (a)~~ ~~Relevant to claims for epoxy (b)~~			~~No use relevant to claim~~
		Example 5	Example 6	Example 7	Comparative example 1
Epoxy resin	Epoxy (a)	Epoxy 5 (93.8 pbw)	Epoxy 2 (112.5 pbw)	Epoxy 5 (93.8 pbw)	Epoxy 3 (106 pbw)
	Epoxy (b)	Epoxy 7 (25 pbw)	Epoxy 7 (10 pbw)	Epoxy 7 (25 pbw)	—
		—	—	—	Epoxy 11 (15 pbw)

Curing agent		Curing agent 1 (38.6 pbw)	Curing agent 1 (39.5 pbw)	Curing agent 1 (38.6 pbw)	Curing agent 1 (44.8 pbw)
Curing accelerator		Accelerator 1(0.13 pbw)	Accelerator 1(0.13 pbw)	Accelerator 1(0.13 pbw)	Accelerator 1 (0.13 pbw)
Organic solvent		Organic solvent 1 (8 pbw)	Organic solvent 2 (25 pbw)	Organic solvent 1 (8 pbw)	Organic solvent 1 (26 pbw)
		Organic solvent 2 (19 pbw)	Organic solvent 3 (25 pbw)	Organic solvent 2 (19 pbw)	Organic solvent 2 (10 pbw)
		Organic solvent 3 (19 pbw)		Organic solvent 3 (19 pbw)	
Inorganic filler		Inorganic filler 1 (19 pbw)	Inorganic filler 2 (63.8 pbw)	Inorganic filler 3 (19 pbw)	—
Ratio of epoxy (a) + epoxy (b) as a solid content per whole epoxy resin		100%	100%	100%	85%
Proportion of epoxy (a) as solid content per whole epoxy resin		75%	90%	75%	85%
Bromine content (%) in epoxy resin		27%	23%	27%	16.2
Appearance of prepreg		Good	Good	Good	Lack of resin uniformity
Glass transition temperature		o(135□)	o(134□)	×(105□)	o(143□)
Fire retardancy		V-0	V-0	V-0	V-0
Moldability		o	o	o	o
Curing time for prepreg (second)	60 seconds	o	o	o	o
	80 seconds	o	o	o	o
	100 seconds	o	o	o	o
	140 seconds	o	o	o	o
	180 seconds	o	o	o	o
Coefficient of thermal expansion (αz1)		55 ppm	45 ppm	55 ppm	65 ppm
Heat resistance in oven		270□	270□	279□	265□
Thermal decomposition temperature (weight loss by 5%)		355□	355□	355□	350□

		~~Not relevant to epoxy (a)~~	~~Not relevant~~	
		~~Relevant to claim for epoxy (b)~~	~~No use~~	~~Cured by DICY~~
		Comparative example 2	Comparative example 3	Comparative example 4
Epoxy resin	Epoxy (a)	Epoxy 6 (118.8 pbw)	Epoxy 6 (125 pbw)	Epoxy 6 (106 pbw)
	Epoxy (b)	Epoxy 8 (5 pbw)	—	—
		—	—	Epoxy 11 (15 pbw)
Curing agent		Curing agent 1 (41.7 pbw)	Curing agent 2 (21 pbw)	Curing agent 4 (2.5 pbw)
Curing accelerator		Accelerator 1 (0.13 pbw)	Accelerator 1 (0.13 pbw)	Accelerator 1 (0.05 pbw)

Organic solvent		Organic solvent 2 (33.3 pbw)	Organic solvent 1 (30 pbw)	Organic solvent 1 (13 pbw)
			Organic solvent 2 (10 pbw)	Organic solvent 2 (10.6 pbw)
				Organic solvent 4 (23.6 pbw)
Inorganic filler		—	—	—
Ratio of epoxy (a)+ epoxy (b) as a solid content per whole epoxy resin		100%	100%	—
Proportion of epoxy (a) as solid content per whole epoxy resin		95%	100%	—
Bromine content (%) in epoxy resin		19%	20%	—
Appearance of prepreg		Good	Some non-uniformity with resin	Good
Glass transition temperature		×(122□)	×(120□)	○(135□)
Fire retardancy		V-0	V-0	V-0
Moldability		○	□	○
Curing time for prepreg (second)	60 seconds	○	×	○
	80 seconds	○	○	○
	100 seconds	○	○	○
	140 seconds	○	○	○
	180 seconds	○	○	○
Coefficient of thermal expansion (αz1)		65 ppm	65 ppm	65 ppm
Heat resistance in oven		265□	265□	240□
Thermal decomposition temperature (weight loss by 5%)		350□	350□	310□

Respectfully submitted,

John F. Hoffman
Registration No. 26,280

Attorney for Applicants

JFH/nw

BAKER & DANIELS LLP
111 East Wayne Street, Suite 800
Fort Wayne, IN 46802
Telephone: 260-424-8000
Facsimile: 260-460-1700

Enc. Return Postcard

CERTIFICATION OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on: March 16, 2006.

JOHN F. HOFFMAN, REG. NO. 26,280
Name of Registered Representative

Signature

March 16, 2006
Date